# DATA SHEET

Part No.	MN5774
Pait No.	MN5774LD
Backago Codo No	TQFP048-P-0707B
Package Code No.	MLGA051-L-0606

SEMICONDUCTOR COMPANY MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

## MN5774/MN5774LD

#### SD Interface LSIs

#### Overview

The MN5774, MN5774LD are LSIs for SD memory/SDIO card interface.

These LSIs provide half-duplex access to the SD memory/ SDIO card using the host's driver software.

Running the LSIs at 50/40 MHz (SD card clock of 25/20 MHz) allows data transfer at maximum 10/8 MBytes/s.

Also, these LSIs support SDIO command and are best suited for mobile devices requiring general ports.

\*The value for each of the MN5774 and MN5774LD is given usin 50/40 MHz notation, etc. '50 MHz' corresponds to the MN5774 while 40 MHz' corresponds to the MN5774LD.

#### ■ Feature

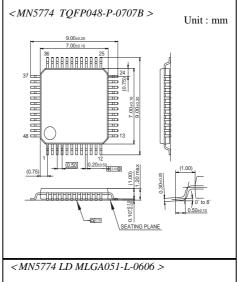
- Mounting area: 36 mm<sup>2</sup> (for MN5774LD only)
- Operating supply voltage: 2.7 V (for MN5774LD only)
- Support SDIO command
- High-speed data transfer: 10/8 MBytes/s (Max.) (when the clock frequency = 50/40 MHz)
- 16-bit asynchronous handshake microprocessor interface
- Provide 1-port for SD memory/SDIO card
- Card detection and write protection
- Do not support CPRM

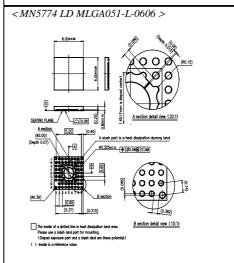
#### Applications

Cellphones, PDAs, DSCs, DVCs, etc.

#### Specifications

#### MN5774/MN5774LD



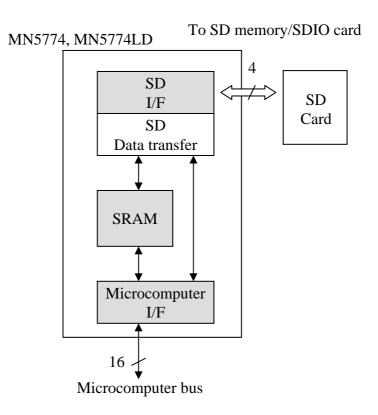


Item	MN5774	MN5774LD
Microprocessor I/F	16-bit asynchronous handshake compatible with the MN10200-series microcomputers, etc.	
Buffer memory	512 bytes $\times$ 2 (256 words $\times$ 16 bits $\times$ 2 : synchronous SRAM)	
Process	0.30 μm, 3-layer metal CMOS	
Clock frequency	50 MHz (Max.)	40 MHz (Max.)
Supply voltage	3.0 V to 3.6 V	2.7 V to 3.6 V
Power consumption	50 mW (50 MHz, VDD = 3.3 V)	40 mW (40 MHz, VDD = 3.3 V)
Package	TQFP048-P-0707B	MLGA051-L-0606

Note: The detailed information for this product is disclosed after non-disclosure agreement between your company and MEI.

SDC00060AEM 2

### ■ Block Diagram



SDC00060AEM 3

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